

Filename: PMP7223 REV_B_bom.xls

Date: 11/23/2012

PMP7223 REV_B BOM

| COUNT | RefDes | Value | Description | Size | Part Number | Mfr |
|-------|----------------|-------------|--|------------------|-----------------|---------|
| 1 | C1 | 22uF | Capacitor, Ceramic, 10V, X5R, 20% | 1206 | Std | Std |
| 1 | C5 | 0.1uF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | Std | Std |
| 1 | C8 | 47nF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | Std | Std |
| 1 | C9 | 100pF | Capacitor, Ceramic, 250V, COG, 10% | 0603 | C1608COG2E101K | TDK |
| 1 | C12 | 22pF | Capacitor, Ceramic, 50V, COG, 10% | 0603 | Std | Std |
| 1 | C13 | 22nF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | Std | Std |
| 1 | C100 | 220pF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | Std | Std |
| 1 | C101 | 2.2nF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | Std | Std |
| 2 | C2 C7 | 10uF | Capacitor, OSCON, 10V, 350milliohm, 20% | 0.157 inch | 10SV10M | Sanyo |
| 5 | C3-4 C6 C10-11 | 10uF | Capacitor, Ceramic Chip, 25V, X5R, ±10% | 1206 | C3216X5R1E106K | TDK |
| 1 | D2 | 10V | Diode, Zener, 10.5-mA, 10-V | SOD123 | MMSZ5240BT1 | On Semi |
| 1 | D6 | 13V | Diode, Zener, 9.5-mA, 13-V | SOD123 | MMSZ5243BT1 | On Semi |
| 1 | D7 | SMD110PL | Diode, Schottky, 1A, 100V | SOD-123 | SMD110PL | MCC |
| 2 | D1 D4 | MBR0540 | Diode, Schottky, 0.5A, 40V | SOD-123 | MBR0540TxG | On Semi |
| 2 | J1 J3 | ED1514 | Terminal Block, 2-pin, 6-A, 3.5mm | 0.27 x 0.25 | ED1514 | OST |
| 2 | J2 J4 | ED555/2DS | Terminal Block, 2-pin, 6-A, 3.5mm | 0.27 x 0.25 inch | ED555/2DS | OST |
| 1 | R1 | 1K | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R2 | 82 | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R3 | 0 | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R4 | 10K | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R5 | 221K | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R6 | 47.5K | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R7 | 16.2K | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R100 | 8.21K | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | T1 | 10 uH | Transformer, ±10% | 17.2x22.3 mm | 750313527 | Wuerth |
| 1 | U1 | TLV1117I-33 | IC, 3.3V, 800mA LDO Voltage Regulators | SOT-223 | TLV1117I-33CDCY | TI |
| 1 | U2 | TLV1117I-50 | IC, 5V, 800mA LDO Voltage Regulators | SOT-223 | TLV1117I-50CDCY | TI |
| 1 | U3 | TPS61165DRV | IC, 1.2MHz/1.2A PWM | SON-6 | TPS61165DRV | TI |
| 1 | U4 | TCMT1107 | IC, Photocoupler, 80-160% CTR | MF4 | TCMT1107 | Vishay |
| 1 | U5 | LMV431A | IC, Low-Voltage Adjustable Shunt Regulator | SOT23-3 | LMV431AIMFx | TI |

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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